

# Multicore Lead-Free Solder Wire - 502

## Product Images

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## Description

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- No-clean, clear residue, minimal activation for increased wetting speed
- Composition: 95.5% SN, 3.8% Ag, 0.7% CU
- Halide Content: 0.2%
- IPC Class: ROM1
- Flux Content by Weight: 3%